



# Effect of moisture content and its distribution throughout the mat on thick waferboard

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Physical properties

Panels

Binders

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Abstract: The relationship of press closing time, strength properties and density profile of thick waferboard panels to mat moisture content was demonstrated in this study. Lower mat moisture contents were found to increase press clothing time but permit faster binder curing. When the distribution of mat moisture was higher in the face layers, shorter press times were achievable and a significant densification of the panel was observed.

Waferboard - Panels - Physical Properties

Moisture content

Binders

Curing

## Documents



E1564.pdf

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